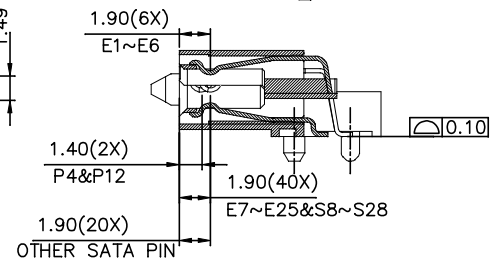
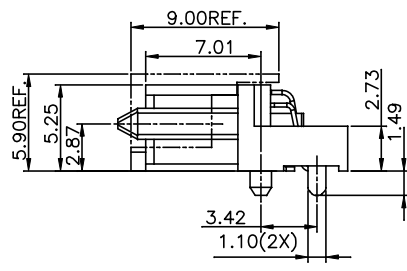
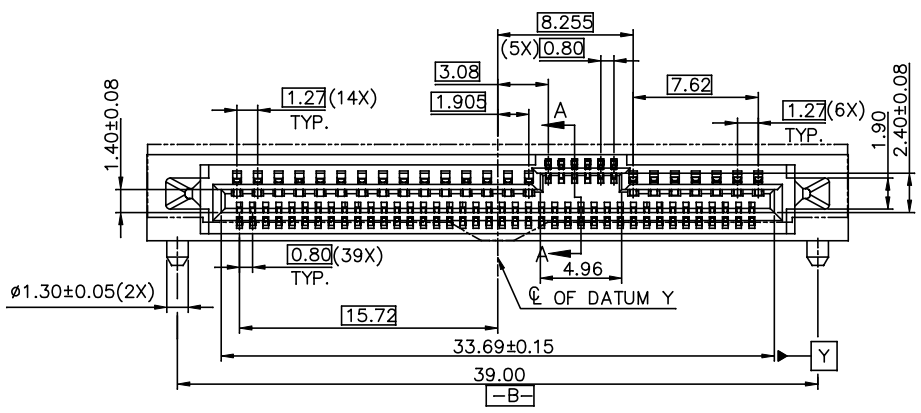
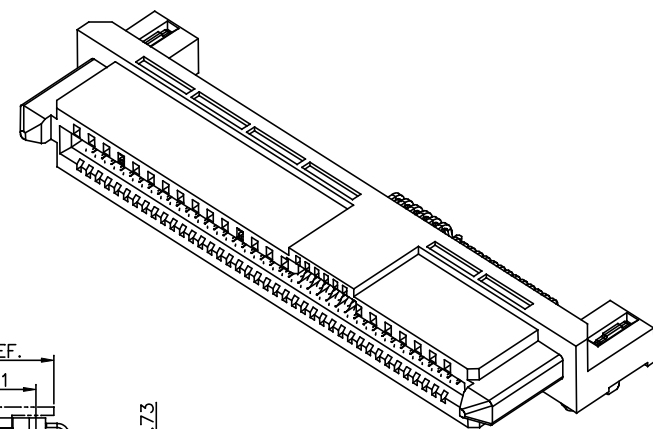
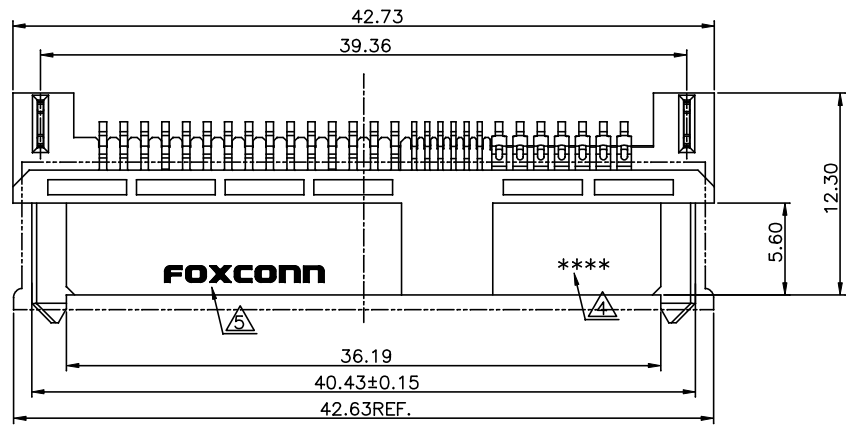


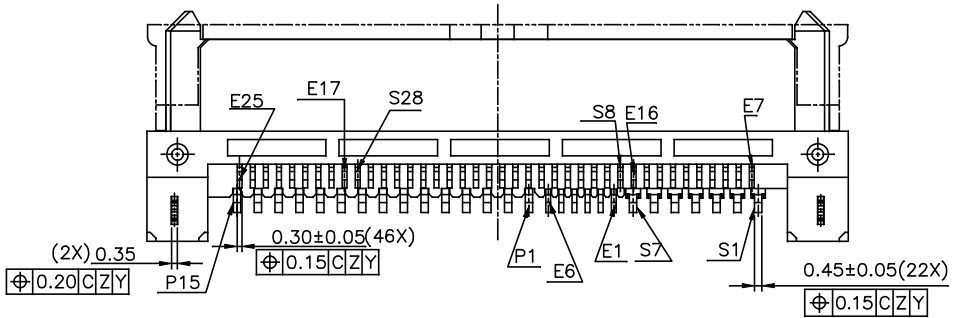
REV.	ECN.	NO.	APPD.
A	BC-17-0025903		Shih-wei Hsiao
B	BC-17-0028367		Shih-wei Hsiao

NOTES: UNLESS OTHERWISE SPECIFIED

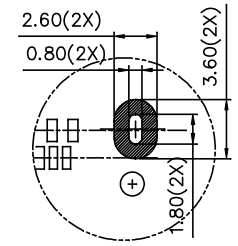
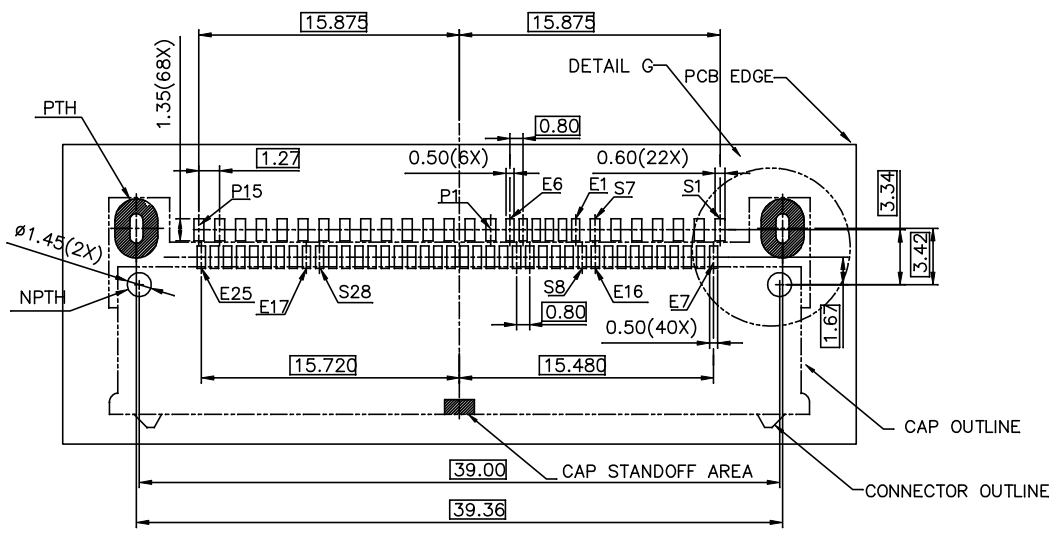
- DIMENSIONS SHALL BE INTERPRETED PER ASME Y14.5-2009.
- SPEC. OF PROD. ARE SHOWN ON DRAWING "303-0300-3301".
- MATERIAL OF PARTS ARE SHOWN ON DRAWING "303-0500-3301".
- DATE CODE: PLEASE REFER TO FOXCONN'S DOC. "SQ-3B0-070".
- THE "FOXCONN" LOGO IS LOCATED APPROX. AS SHOWN.
- PRODUCT No. MATRIX : PLEASE REFER TO DRAWING "303-0500-3301".
- HARMFUL MATERIAL CONTROL PLEASE FOLLOW FOXCONN'S DOC. "EPI12".
- PLEASE CONTACT FOXCONN'S SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.



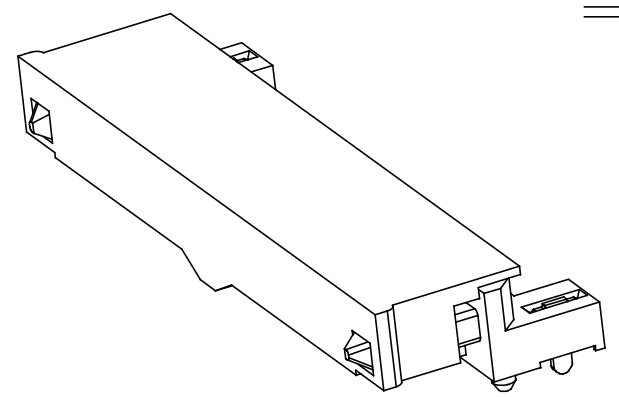
SEC: A-A  
SCALE 1:1



X. $\pm$	X° $\pm 1^\circ$	UNITS	mm	NAME (INTENDED USE)	<b>FOXCONN</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X $\pm 0.20$	.X° $\pm$	MAT'L		R/A, SMT, REC. PCI-e SAS	
.XX $\pm 0.15$	.XX° $\pm$			PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX $\pm 0.10$	.XXX° $\pm$	FINISH		LDP268*-13A50-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				APPD: Shih-Wei Hsiao	DWG NO.:
				CHKD: Yen-chih.Chang	303-0000-3301
				DR: Meng Liu 9/21'17	SCALE SHEET REV. N/A 1/3 B



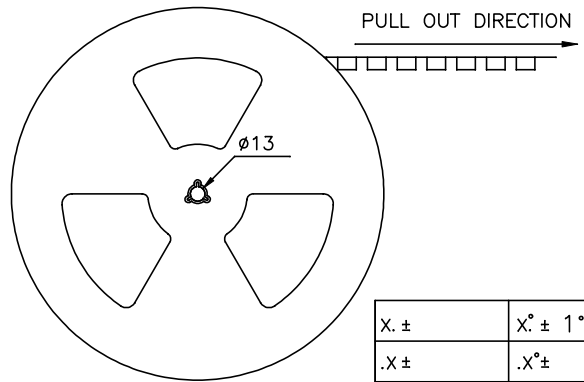
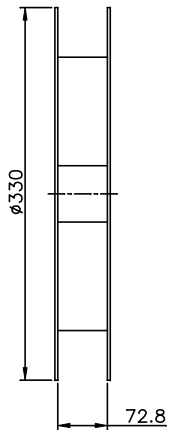
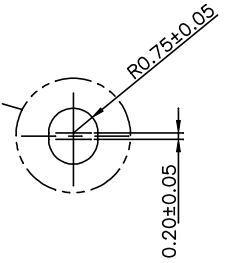
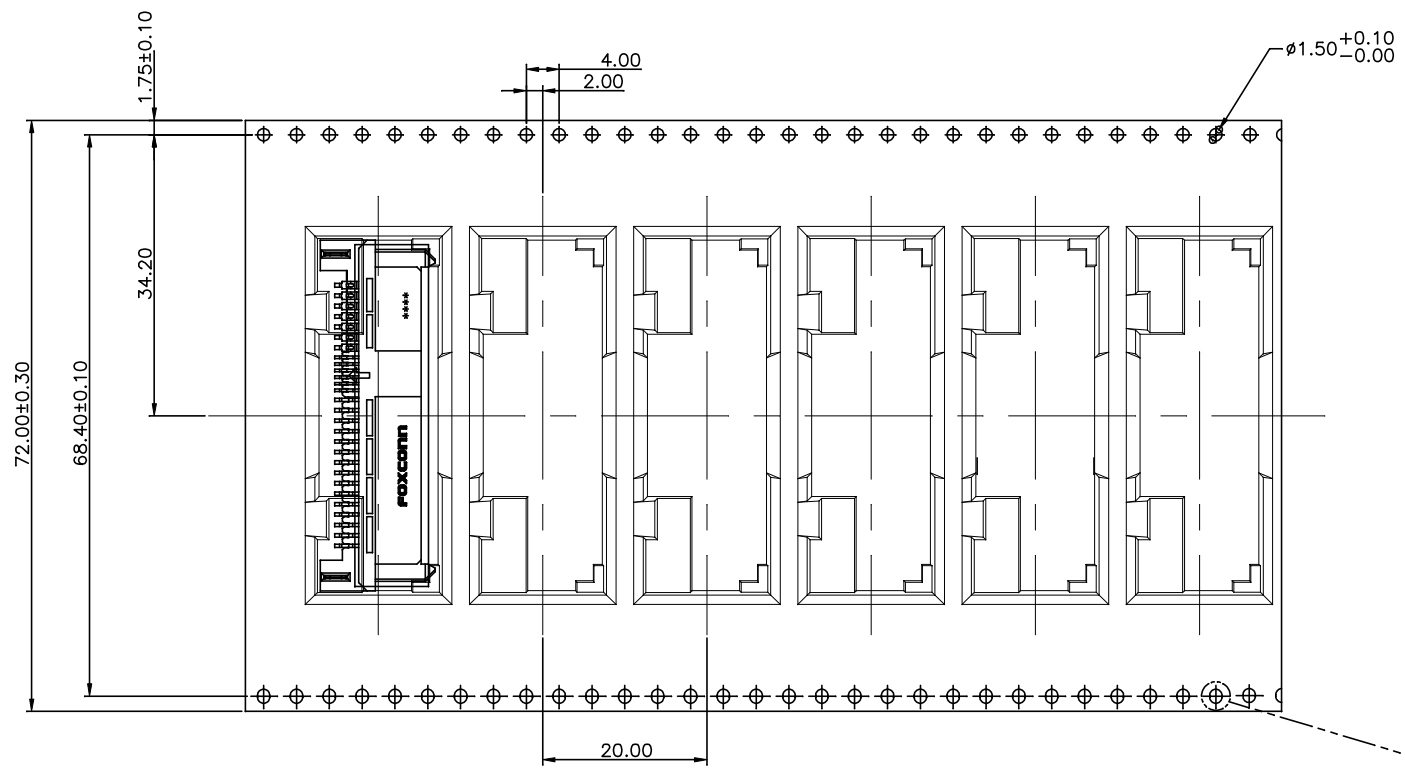
RECOMMENDED P.C.B. LAYOUT(TOLERANCE: ±0.05)  
 COMPONENT TOP VIEW



WITH CAP VIEW

X. ±	X°. ± 1°	UNITS mm	NAME(INTENDED USE)	<b>FOXCONN®</b>
.X ± 0.20	.X° ±	MAT'L	R/A , SMT , REC. PCI-e SAS	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX ± 0.15	.XX° ±	FINISH	PART NO.(INTENDED USE)	CLASS:
.XXX ± 0.10	.XXX° ±		LDP268*-13A50-*H	<input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: Shih-Wei Hsiao	TITLE: CUSTOMER DRAWING
			Q'TY	DWG NO.: 303-0000-3301
			CHKD: Yen-chih.Chang	SCALE SHEET REV.
DR: Meng Liu 9/21'17			N/A 2/3 B	

REV.	ECN.	NO.	APPD.



X. ±	X°. ± 1°	UNITS mm	NAME(INTENDED USE)	<b>FOXCONN®</b>
.X ±	.X° ±	MAT'L	R/A , SMT , REC. PCI-e SAS	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX ±	.XX° ±	FINISH	PART NO.(INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		LDP268*-13A50-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: Shih-Wei Hsiao	DWG NO.:
			CHKD: Yen-chih.Chang	303-0000-3301
			DR: Meng Liu 9/21'17	
				SCALE SHEET REV.
				N/A 3/3 B

REV.	ECN. NO.	APPD.
A	BC-18-0002448	Shih-wei Hsiao

# SPECIFICATIONS :

## 1. MATERIAL AND FINISH :

### 1-1. HOUSING :

HIGH TEMP. THERMOPLASTIC, UL94V-0 , COLOR BLACK.

### 1-2. CAP :

HIGH TEMP. THERMOPLASTIC, UL94V-0 , COLOR BLACK.

### 1-3. S-ATA CONTACT :

COPPER ALLOY, 0.25mm THICK. NICKEL PLATING OVER ALL, THICKNESS 50u" MIN. MATTE-TIN PLATING OVER NICKEL, THICKNESS 100u" MIN. ON SOLDER AREA, GOLD PLATING OVER NICKEL ON CONTACT AREA,

### 1-4. SAS CONTACT :

COPPER ALLOY, 0.25mm THICK. NICKEL PLATING OVER ALL, THICKNESS 50u" MIN. MATTE-TIN PLATING OVER NICKEL, THICKNESS 100u" MIN. ON SOLDER AREA, GOLD PLATING OVER NICKEL ON CONTACT AREA,

### 1-5. PCI-e SAS PIN

COPPER ALLOY, 0.25mm THICK. NICKEL PLATING OVER ALL, THICKNESS 50u"MIN. MATTE-TIN PLATING OVER NICKEL, ON SOLDER AREA, THICKNESS 100u" MIN. GOLD PLATING OVER NICKEL ON CONTACT AREA,

### 1-6. BOARD LOCK:

C5191, NICKEL PLATING OVER ALL, THICKNESS 50u" MIN., TIN PLATING OVER ALL, THICKNESS 100u"MIN..

### 1-7. HARMFUL MATERIAL CONTROL PLAESE FOLLOW DOC. NO."EPI12"

### 1-8. THE CONCENTRATIONS OF Br&Cl CAN SATISFYTHE REQUIREMENTS OF HALOGEN-FREE IN DOC. EPI12.

## 2. ELECTRICAL :

2-1. LOW LEVEL CONTACT RESISTANCE : 30 MILLIOHMS MAX. INITIAL.

2-2. DIELECTRIC WITHSTANDING VOLTAGE : EIA-364-20, NO BREAKDOWN.

2-3. INSULATION RESISTANCE : EIA-364-21, 1000 MEGAOHMS MIN.

2-4. TEMPERATURE RISE(VIA CURRENT CYCLING) POWER SECTION ONLY (P1 THROUGH P15) : THE TEMPERATURE RISE SHALL NOT EXCEED 30°C.

## 3. MECHANICAL:

3-1. MATING FORCE: EIA-364-13, 59N MAX.

3-2. UNMATING FORCE: EIA-364-13, 6N MIN. INITIAL AND AFTER DURABILITY

3-3. DURABILITY: 500 CYCLES

3-4. PHYSICAL SHOCK: PASS EIA-364-27, CONDITION H.

3-5. VIBRATION: PASS EIA-364-28, CONDITION VII TEST LETTER A.


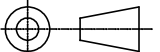
## 4. ENVIRONMENTAL:

4-1. HUMIDITY: PASS EIA-364-31, METHOD II TEST CONDITION A.

4-2. OPERATING TEMPERATURE:-55° TO +85°.

4-3. TEMPERATURE LIFT:PASS EIA-364-17,TEST CONDITION III, METHOD A

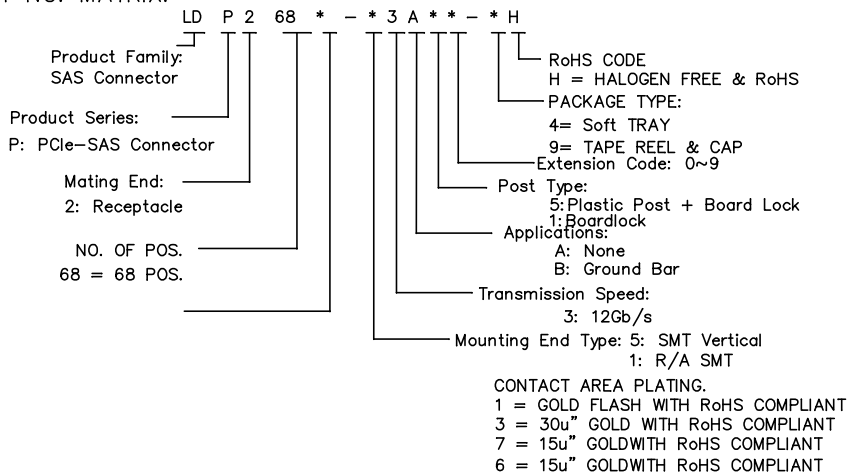
4-4. MIXED FLOWING GAS:PASS EIA-364-65, CLASS 2A.

X.±	X.* ±	UNITS mm	NAME(INTENDED USE) PCI-e SAS 68 PIN REC. R/T SMT	 <b>FOXCONN INTERCONNECT TECHNOLOGY LIMITED.</b>						
.X±	.X* ±	MAT'L	PART NO.(INTENDED USE) LDP268*-13A*0-*H							
.XX±	.XX* ±	FINISH	APPD: Shih-Wei Hsiao	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL TITLE: SPECIFICATION SHEET						
.XXX±	.XXX* ±		Q'TY	CHKD: Yen-chih.Chang	DWG NO.: 303-0300-3301					
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			SCALE	SHEET	REV.					
N/A	1/1	A								


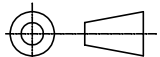
REV.	ECN. NO.	APPD.
A	BC-18-0002476	Shih-wei Hsiao

ITEM	DESC.	Q'TY	MATERIAL	TREATMENT	REMARK
1	HOUSING	1	HIGH TEMPERATURE THERMO-PLASTIC, UL 94V-0	INJECTION MOLDING	
2	CAP	1	HIGH TEMPERATURE THERMO-PLASTIC, UL 94V-0	INJECTION MOLDING	
3	SATA PIN	22	COPPER ALLOY	A) NICKEL PLATING OVER ALL THICKNESS : 50 u" MIN. B) MATTE-TIN PLATING OVER NICKEL. THICKNESS : 100 u" MIN ON SOLDER AREA C) GOLD PLATING OVER NICKEL. ON CONTACT AREA	
4	SAS PIN & PCI-e PIN	46	COPPER ALLOY	A) NICKEL PLATING OVER ALL THICKNESS : 50 u" MIN. B) MATTE-TIN PLATING OVER NICKEL. THICKNESS : 100 u" MIN ON SOLDER AREA C) GOLD PLATING OVER NICKEL. ON CONTACT AREA	
5	BOARD LOCK	2	COPPER ALLOY	A) NICKEL PLATING OVER ALL THICKNESS : 50u"MIN. B) MATTE-TIN PLATING OVER NICKEL. THICKNESS : 100u"MIN ON SOLDER AREA	

NOTES : 1. HARMFUL MATERIAL CONTROL PLEASE FOLLOW DOC. NO. "EPI12"  
 2. THE CONCENTRATIONS OF Br&Cl CAN SATISFY THE REQUIREMENTS OF HALOGEN-FREE IN DOC. EPI12.  
 3. PRODUCT NO. MATRIX:



4. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

X. ±	X.° ±	UNITS mm	NAME (INTENDED USE) PCI-e SAS 68 PIN REC. R/T SMT	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ±	.X° ±	MAT'L	PART NO. (INTENDED USE) LDP268*-13A*0-*H	
.XX ±	.XX° ±	FINISH	APPD: Shih-Wei Hsiao	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		Q'TY	CHKD: Yen-chih.Chang
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			DRAW: Meng Liu 01/13 '18	DWG NO.: 303-0500-3301
				SCALE: N/A